

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No.**
Kazuto NISHIDA : **Docket No.00177/526327**
Serial No. 09/331,763 : **Group Art Unit 3727**
Filed June 25, 1999 : **Examiner J. Merek**

METHOD AND APPARATUS FOR MOUNTING ELECTRONIC COMPONENT ON CIRCUIT BOARD

AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

**THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975**

Sir:

Responsive to the Office Action mailed October 25, 2001, the time for responding thereto being extended for three months in accordance with a Petition for Extension submitted herewith, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 30, line 3, with the following rewritten paragraph:

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In the state in which the warp of the circuit board 4 is corrected, heat of, for example, 140 to 230°C is applied to the thermosetting resin sheet 6 located between the IC chip 1 and the circuit board 4 for about several seconds to 20 seconds, so that this thermosetting resin sheet 6 is hardened. In this stage, because of the composition of the circuit board, and the temperature and duration of the heating of the circuit board, the circuit board is softened to some extent. This softening aids in the warp of the circuit board being corrected. Also, the thermosetting resin that constitutes the thermosetting resin sheet 6 flows at the beginning to encapsulate the IC chip 1 up to its edges. The thermosetting resin is naturally softened in the early stage when heated because it is resin, and